

View Online at <https://aerobasegroup.com/nsn/8040-01-145-1053>

**Physical Form:**

Paste

**Specific Usage Design:**

Bonding semiconductor chips in the fabrication of hybrid circuits; die attaching mos chips

**Shelf Life:**

N/a

**Unit Of Measure:**

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**Demilitarization:**

No

**Fig:**

A535p0